

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

24.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1	A00 B00
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2	
C-RS-FR4-ML-0.203mm-035+035-TG150-HF-...	50203019	35	L2	3	
		203			
		35	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		4	
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	5	

Thickness after Pressing

B00: 390 µm Tol+: 100 µm Tol-: 100 µm Dmax: 490 µm Dmin: 290 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 500 µm Tol+: 100 µm Tol-: 100 µm Dmax: 600 µm Dmin: 400 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 415 µm

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